

#### **Overview**

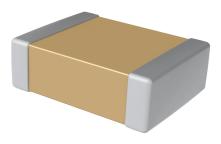
KEMET's Y5V dielectric features an 85°C maximum operating temperature and is considered "general-purpose." The Electronics Industries Alliance (EIA) characterizes Y5V dielectric as a Class III material. Components of this classification are fixed, ceramic dielectric capacitors, suited for bypass and decoupling or other applications in which dielectric losses, high insulation resistance and capacitance stability are not of major importance. Y5V exhibits a predictable change in capacitance with respect to time and voltage, and displays wide variations in capacitance with reference to ambient temperature. Capacitance change is limited to +22%, -82% from -30°C to +85°C.

#### **Benefits**

- -30°C to +85°C operating temperature range
- · Lead (Pb)-free, RoHS and REACH compliant
- EIA 0402, 0603, 0805, 1206, and 1210 case sizes
- DC voltage ratings of 6.3 V, 10 V, 16 V, 25 V, and 50 V
- Capacitance offerings ranging from 0.022  $\mu$ F to 22  $\mu$ F
- Available capacitance tolerance of ±20% and +80%/-20%
- · Non-polar device, minimizing installation concerns
- 100% pure matte tin-plated termination finish that allows for excellent solderability

#### **Applications**

Typical applications include limited temperature, decoupling and bypass.



#### **Ordering Information**

С	1210	C	226	Z	4	V	Α	С	TU
Ceramic	Case Size (L" x W")	Specification/ Series	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Dielectric	Failure Rate/ Design	Termination Finish <sup>1</sup>	Packaging/ Grade (C-Spec)
	0402 0603 0805 1206 1210	C = Standard	Two significant digits + number of zeros	M = ±20% Z = +80%/-20%	9 = 6.3 8 = 10 4 = 16 3 = 25 5 = 50	V = Y5V	A = N/A	C = 100% Matte Sn	See "Packaging C-Spec Ordering Options Table" below

<sup>1</sup> Additional termination finish options may be available. Contact KEMET for details.



### Packaging C-Spec Ordering Options Table

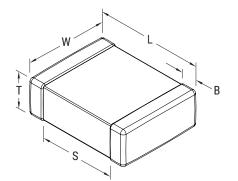
Packaging Type <sup>1</sup>	Packaging/Grade Ordering Code (C-Spec)
Bulk Bag/Unmarked	Not required (Blank)
7" Reel/Unmarked	TU
13" Reel/Unmarked	7411 (EIA 0603 and smaller case sizes) 7210 (EIA 0805 and larger case sizes)
7" Reel/Marked	ТМ
13" Reel/Marked	7040 (EIA 0603 and smaller case sizes) 7215 (EIA 0805 and larger case sizes)
7" Reel/Unmarked/2mm pitch <sup>2</sup>	7081
13" Reel/Unmarked/2mm pitch <sup>2</sup>	7082

<sup>1</sup> Default packaging is "Bulk Bag". An ordering code C-Spec is not required for "Bulk Bag" packaging.

<sup>1</sup> The terms "Marked" and "Unmarked" pertain to laser marking option of capacitors. All packaging options labeled as "Unmarked" will contain capacitors that have not been laser marked. Please contact KEMET if you require a laser marked option. For more information see "Capacitor Marking".

<sup>2</sup> The 2 mm pitch option allows for double the packaging quantity of capacitors on a given reel size. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".

#### **Dimensions – Millimeters (Inches)**



EIA Size Code	Metric Size Code	L Length	W Width	T Thickness	B Bandwidth	S Separation Minimum	Mounting Technique
0402	1005	1.00 (0.040) ±0.05 (0.002)	0.50 (0.020) ±0.05 (0.002)		0.30 (0.012) ±0.10 (0.004)	0.30 (0.012)	Solder Reflow Only
0603	1608	1.60 (0.063) ±0.15 (0.006)	0.80 (0.032) ±0.15 (0.006)		0.35 (0.014) ±0.15 (0.006)	0.70 (0.028)	
0805	2012	2.00 (0.079) ±0.20 (0.008)	1.25 (0.049) ±0.20 (0.008)	See Table 2 for Thickness	0.50 (0.02) ±0.25 (0.010)	0.75 (0.030)	Solder Wave or Solder Reflow
1206	3216	3.20 (0.126) ±0.20 (0.008)	1.60 (0.063) ±0.20 (0.008)		0.50 (0.02) ±0.25 (0.010)	N/A	
1210	3225	3.20 (0.126) ±0.20 (0.008)	2.50 (0.098) ±0.20 (0.008)		0.50 (0.02) ±0.25 (0.010)	N/A	Solder Reflow Only



### **Qualification/Certification**

Commercial Grade products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 4, Performance & Reliability.

#### **Environmental Compliance**

Lead (Pb)-free, RoHS, and REACH compliant without exemptions.

### **Electrical Parameters/Characteristics**

Item	Parameters/Characteristics
Operating Temperature Range	-30°C to +85°C
Capacitance Change with Reference to +25°C and 0 Vdc Applied (TCC)	+22%, -82%
<sup>1</sup> Aging Rate (Maximum % Capacitance Loss/Decade Hour)	7.0%
<sup>2</sup> Dielectric Withstanding Voltage (DWV)	250% of rated voltage (5±1 seconds and charge/discharge not exceeding 50mA)
<sup>3</sup> Dissipation Factor (DF) Maximum Limit at 25°C	10% (6.3 V and 10 V), 7% (16 V and 25 V) and 5% (50 V )
<sup>4</sup> Insulation Resistance (IR) Minimum Limit at 25°C	See Insulation Resistance Limit Table (Rated voltage applied for 120±5 seconds at 25°C)

<sup>1</sup>Regarding Aging Rate: Capacitance measurements (including tolerance) are indexed to a referee time of 48 or 1,000 hours. Please refer to a part number specific datasheet for referee time details.

<sup>2</sup>DWV is the voltage a capacitor can withstand (survive) for a short period of time. It exceeds the nominal and continuous working voltage of the capacitor.

<sup>3</sup> Capacitance and dissipation factor (DF) measured under the following conditions:

1kHz ± 50Hz and 1.0 ± 0.2 Vrms if capacitance  $\leq$ 10 $\mu$ F

120Hz ± 10Hz and 0.5 ± 0.1 Vrms if capacitance >10µF

<sup>4</sup> To obtain IR limit, divide  $M\Omega$ - $\mu$ F value by the capacitance and compare to G $\Omega$  limit. Select the lower of the two limits.

Note: When measuring capacitance it is important to ensure the set voltage level is held constant. The HP4284 & Agilent E4980 have a feature known as Automatic Level Control (ALC). The ALC feature should be switched to "ON".

# **Post Environmental Limits**

High Temperature Life, Biased Humidity, Moisture Resistance											
Dielectric	Rated DC Voltage	Capacitance Value	Dissipation Factor (Maximum %)	Capacitance Shift	Insulation Resistance						
	> 25		7.5								
Y5V	16/25	All	10.0	±30%	10% of Initial Limit						
	< 16		15.0		2						

#### **Insulation Resistance Limit Table**

EIA Case Size	100 Megohm Microfarads or 10 GΩ	50 Megohm Microfarads or 10 GΩ
All	≥ 16 V	≤ 10 V



# Table 1 – Capacitance Range/Selection Waterfall (0402 – 1210 Case Sizes)

		Case Sei	Size/ ries	C	)40	2C		C06	030	;		С	)80	5C			<b>C</b> 1	120	6C			C	1210	C	
Capacitance	Capacitance	Voltag	e Code	9	8	4	9	8	4	3	9	8	4	3	5	9	8	4	3	5	9	8	4	3	5
Capacitance	Code	Rated Volt	age (VDC)	6.3	10	16	6.3	10	16	25	6.3	10	16	25	50	6.3	10	16	25	50	6.3	10	16	25	50
		Capacitanc	eitance Tolerance Product Availability and Chip Thickness Codes See Table 2 for Chip Thickness Dimensions																						
22,000 pF	223	М	Z	BB	BB	BB	CF	CF	CF	CF	DN	DN	DN	DN	DN										
27,000 pF	273	М	Z	BB	BB	BB	CF	CF	CF	CF	DN	DN	DN	DN	DN										
33,000 pF	333	М	Z	BB	BB	BB	CF	CF	CF	CF	DN	DN	DN	DN	DN										
39,000 pF	393	М	Z	BB	BB	BB	CF	CF	CF	CF	DP	DP	DP	DP	DP										
47,000 pF	473	М	Z	BB	BB	BB	CF	CF	CF	CF	DO	DO	DO	DO	DO										
56,000 pF	563	М	Z	BB	BB	BB	CF	CF	CF	CF	DP	DP	DP	DP	DP										
68,000 pF	683	М	Z	BB	BB	BB	CF	CF	CF	CF	DP	DP	DP	DP	DP						1				
82,000 pF	823	М	Z	BB	BB	BB	CF	CF	CF	CF	DP	DP	DP	DP	DP										
0.10 µF	104	М	Z	BB	BB	BB	CG	CG	CG	CG	DN	DN	DN	DN	DN										
0.12 µF	124	М	Z				CG	CG	CG	CG	DN	DN	DN	DN											
0.15 µF	154	М	Z				CG	CG	CG	CG	DN	DN	DN	DN											
0.18 µF	184	М	Z				CG	CG	CG	CG	DN	DN	DN	DN											
0.22 µF	224	М	Z	BB			CG	CG	CG	CG	DN	DN	DN	DN	DG	EC	EC	EC	EC		FD	FD	FD	FD	FD
0.27 µF	274	М	Z				CG	CG	CG	CG	DN	DN	DN	DN		EB	EB	EB	EB		FD	FD	FD	FD	FD
0.33 µF	334	М	Z				CG	CG	CG	CG	DG	DG	DG	DG		EB	EB	EB	EB		FD	FD	FD	FD	FD
0.39 µF	394	М	Z				CG	CG	CG		DN	DN	DN	DN		EB	EB	EB	EB		FD	FD	FD	FD	FD
0.47 µF	474	М	Z	BB			CG	CG	CG		DG	DG	DG	DG		EC	EC	EC	EC		FD	FD	FD	FD	FD
0.56 µF	564	М	Z				CG	CG			DP	DP	DP	DP		EB	EB	EB	EB		FD	FD	FD	FD	FD
0.68 µF	684	М	Z				CG	CG			DP	DP	DP	DG		EB	EB	EB	EB		FD	FD	FD	FD	FD
0.82 µF	824	М	Z				CG	CG			DG	DG	DG	DG		EB	EB	EB	EB		FF	FF	FF	FF	FF
1.0 µF	105	М	Z	BB	BB		CG	CG	CG	CG	DP	DP	DP	DG	DG	EP	EP	EP	EP		FH	FH	FH	FH	FH
1.2 μF	125	М	Z								DN	DN	DN			EC	EC	EC			FD	FD	FD		
1.5 μF	155	М	Z								DN	DN	DN			EC	EC	EC			FD	FD	FD		
1.8 µF	185	М	Z								DP	DP	DP			ED	ED	ED			FD	FD	FD		
2.2 µF	225	М	Z	BB	BB						DG	DG	DG			EC	EC	EC			FJ	FJ	FJ		
3.3 µF	335	М	Z								DL	DL	DG			EH	EH	EH			FE	FE	FE	1	
4.7 μF	475	М	Z								DG	DG	DG			EH²	EH <sup>2</sup>	EH <sup>2</sup>			FT	FT	FT	1	
5.6 µF	565	М	Z								DF	DF				EJ	EJ	EJ			FG	FG	FG	1	
6.8 µF	685	М	Z								DG	DG				EJ	EJ				FH	FH	FH	1	
10 µF	106	М	Z								DG	DG				EH	EH	EH	EH		FT <sup>2</sup>	FT <sup>2</sup>	FT <sup>2</sup>		
15 µF	156	М	Z																		FH	FH	FH		
22 µF	226	М	Z													EH	EH				FT <sup>2</sup>	FT <sup>2</sup>	FS	FS	
		Rated Volt	age (VDC)	6.3	9	16	6.3	9	16	25	6.3	9	16	25	50	6.3	9	16	25	50	6.3	9	16	25	50
Capacitance	Capacitance	Voltag	Voltage Code		8	4	9	8	4	3	9	8	4	3	5	9	8	4	3	5	9	8	4	3	5
	Code		Size/ ries	c	0402	20		C06	03C			C	0805	iC			C	1206	C			C	1210	C	

xx<sup>2</sup> Only available in Z tolerance.



Thickness	Case	Thickness ±	Paper Q	uantity <sup>1</sup>	Plastic (	Quantity	
Code	Size	Range (mm)	7" Reel	13" Reel	7" Reel	13" Reel	
BB	0402	0.50 ± 0.05	10,000	50,000	0	0	
CF	0603	0.80 ± 0.07*	4,000	15,000	0	0	
CG	0603	0.80 ± 0.10*	4,000	15,000	0	0	
DN	0805	0.78 ± 0.10*	4,000	15,000	0	0	
DO	0805	0.80 ± 0.10*	4,000	15,000	0	0	
DP	0805	0.90 ± 0.10*	4,000	15,000	0	0	
DL	0805	0.95 ± 0.10	0	0	4,000	10,000	
DF	0805	1.10 ± 0.10	0	0	2,500	10,000	
DG	0805	1.25 ± 0.15	0	0	2,500	10,000	
EB	1206	0.78 ± 0.10	4,000	10,000	4,000	10,000	
EC	1206	0.90 ± 0.10	0	0	4,000	10,000	
ED	1206	1.00 ± 0.10	0	0	2,500	10,000	
EP	1206	1.20 ± 0.20	0	0	2,500	10,000	
EH	1206	1.60 ± 0.20	0	0	2,000	8,000	
EJ	1206	1.70 ± 0.20	0	0	2,000	8,000	
FD	1210	0.95 ± 0.10	0	0	4,000	10,000	
FE	1210	1.00 ± 0.10	0	0	2,500	10,000	
FF	1210	1.10 ± 0.10	0	0	2,500	10,000	
FG	1210	1.25 ± 0.15	0	0	2,500	10,000	
FH	1210	1.55 ± 0.15	0	0	2,000	8,000	
FJ	1210	1.85 ± 0.20	0	0	2,000	8,000	
FT	1210	1.90 ± 0.20	0	0	2,000	8,000	
FS	1210	2.50 ± 0.30	0	0	1,000	4,000	
Thickness	Case	Thickness ±	7" Reel	13" Reel	7" Reel	13" Reel	
Code	Size1	Range (mm)	Paper Q	uantity <sup>1</sup>	Plastic Quantity		

#### Table 2A – Chip Thickness/Tape & Reel Packaging Quantities

Package quantity based on finished chip thickness specifications.

<sup>1</sup> If ordering using the 2 mm Tape and Reel pitch option, the packaging quantity outlined in the table above will be doubled. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".



#### Table 2B – Bulk Packaging Quantities

Deeker		Loose Pa	ackaging				
Раскау	ing Type	Bulk Bag (default)					
Packagin	g C-Spec <sup>1</sup>	N/	/A <sup>2</sup>				
Case	Size	Packaging Quantities (	pieces/unit packaging)				
EIA (in)	Metric (mm)	Minimum	Maximum				
0402	1005						
0603	1608						
0805	2012		50,000				
1206	3216						
1210	3225	- 1					
1808	4520						
1812	4532						
1825	4564		20,000				
2220	5650						
2225	5664						

<sup>1</sup> The "Packaging C-Spec" is a 4 to 8 digit code which identifies the packaging type and/or product grade. When ordering, the proper code must be included in the 15th through 22nd character positions of the ordering code. See "Ordering Information" section of this document for further details. Commercial Grade product ordered without a packaging C-Spec will default to our standard "Bulk Bag" packaging. Contact KEMET if you require a bulk bag packaging option for Automotive Grade products.

<sup>2</sup> A packaging C-Spec (see note 1 above) is not required for "Bulk Bag" packaging (excluding Anti-Static Bulk Bag and Automotive Grade products). The 15th through 22nd character positions of the ordering code should be left blank. All product ordered without a packaging C-Spec will default to our standard "Bulk Bag" packaging.



#### Table 3 – Chip Capacitor Land Pattern Design Recommendations per IPC-7351

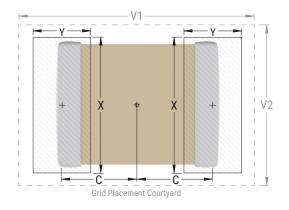
EIA Size Code	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)						Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)					
Coue	Coue	C	Y	X	V1	V2	C	Y	X	V1	V2	C	Y	X	V1	V2		
0402	1005	0.50	0.72	0.72	2.20	1.20	0.45	0.62	0.62	1.90	1.00	0.40	0.52	0.52	1.60	0.80		
0603	1608	0.90	1.15	1.10	4.00	2.10	0.80	0.95	1.00	3.10	1.50	0.60	0.75	0.90	2.40	1.20		
0805	2012	1.00	1.35	1.55	4.40	2.60	0.90	1.15	1.45	3.50	2.00	0.75	0.95	1.35	2.80	1.70		
1206	3216	1.60	1.35	1.90	5.60	2.90	1.50	1.15	1.80	4.70	2.30	1.40	0.95	1.70	4.00	2.00		
1210	3225	1.60	1.35	2.80	5.65	3.80	1.50	1.15	2.70	4.70	3.20	1.40	0.95	2.60	4.00	2.90		
1210 <sup>1</sup>	3225	1.50	1.60	2.90	5.60	3.90	1.40	1.40	2.80	4.70	3.30	1.30	1.20	2.70	4.00	3.00		

#### <sup>1</sup> Only for capacitance values $\ge 22 \ \mu F$

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805, and 1206 case sizes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351).

Image below based on Density Level B for an EIA 1210 case size.





#### **Soldering Process**

#### **Recommended Soldering Technique:**

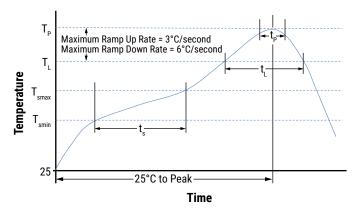
- Solder wave or solder reflow for EIA case sizes 0603, 0805 and 1206
- · All other EIA case sizes are limited to solder reflow only

#### **Recommended Reflow Soldering Profile:**

KEMET's families of surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/ J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Terminat	ion Finish		
Tomeredure	SnPb	100% Matte Sn		
Preheat/Soak				
Temperature Minimum (T <sub>Smin</sub> )	100°C	150°C		
Temperature Maximum (T <sub>Smax</sub> )	150°C	200°C		
Time ( $t_s$ ) from $T_{smin}$ to $T_{smax}$	60 – 120 seconds	60 – 120 seconds		
Ramp-Up Rate (T <sub>L</sub> to T <sub>p</sub> )	3°C/second maximum	3°C/second maximum		
Liquidous Temperature $(T_L)$	183°C	217°C		
Time Above Liquidous ( $t_L$ )	60 – 150 seconds	60 – 150 seconds		
Peak Temperature (T <sub>P</sub> )	235°C	260°C		
Time Within 5°C of Maximum Peak Temperature (t <sub>p</sub> )	20 seconds maximum	30 seconds maximum		
Ramp-Down Rate $(T_p \text{ to } T_L)$	6°C/second maximum	6°C/second maximum		
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum		

Note 1: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.





### Table 4 – Performance & Reliability: Test Methods and Conditions

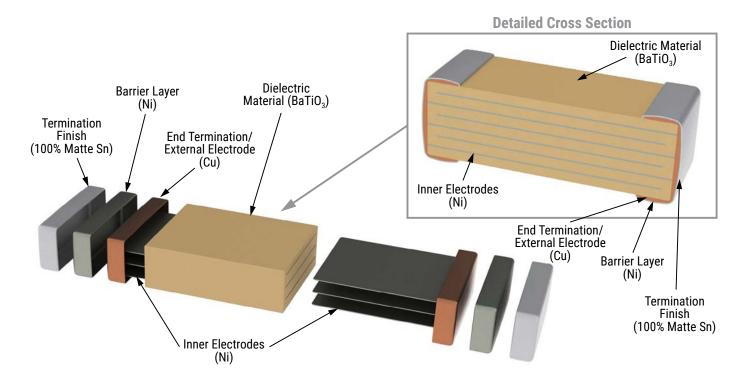
Stress	Reference	Test or Inspection Method
Terminal Strength	JIS-C-6429	Appendix 1, Note: Force of 1.8 kg for 60 seconds.
Board Flex	JIS-C-6429	Appendix 2, Note: Standard termination system – 2.0 mm (minimum) for all except 3 mm for COG. Flexible termination system – 3.0 mm (minimum).
		Magnification 50 X. Conditions:
Caldarability	J-STD-002	a) Method B, 4 hours at 155°C, dry heat at 235°C
Solderability	J-51D-002	b) Method B at 215°C category 3
		c) Method D, category 3 at 260°C
Temperature Cycling	JESD22 Method JA-104	1,000 Cycles (-55°C to +125°C). Measurement at 24 hours +/- 4 hours after test conclusion.
<b>D</b>	MIL-STD-202 Method	Load Humidity: 1,000 hours 85°C/85% RH and rated voltage. Add 100 K ohm resistor. Measurement at 24 hours +/- 4 hours after test conclusion.
Biased Humidity	103	Low Volt Humidity: 1,000 hours 85°C/85% RH and 1.5 V. Add 100 K ohm resistor. Measurement at 24 hours +/- 4 hours after test conclusion.
Moisture Resistance	MIL-STD-202 Method 106	t = 24 hours/cycle. Steps 7a and 7b not required. Measurement at 24 hours +/− 4 hours after test conclusion.
Thermal Shock	MIL-STD-202 Method 107	–55°C/+125°C. Note: Number of cycles required – 300, maximum transfer time – 20 seconds, dwell time – 15 minutes. Air – Air.
High Temperature Life	MIL-STD-202 Method 108 /EIA-198	1,000 hours at 125°C (85°C for X5R, Z5U and Y5V) with 2 X rated voltage applied.
Storage Life	MIL-STD-202 Method 108	150°C, 0 VDC for 1,000 hours.
Vibration	MIL-STD-202 Method 204	5 g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8" X 5" PCB 0.031" thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213, Condition F.
Resistance to Solvents	MIL-STD-202 Method 215	Add aqueous wash chemical, OKEM Clean or equivalent.

#### **Storage and Handling**

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature–reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.



# **Construction (Typical)**



#### **Capacitor Marking (Optional):**

Laser marking option is not available on:

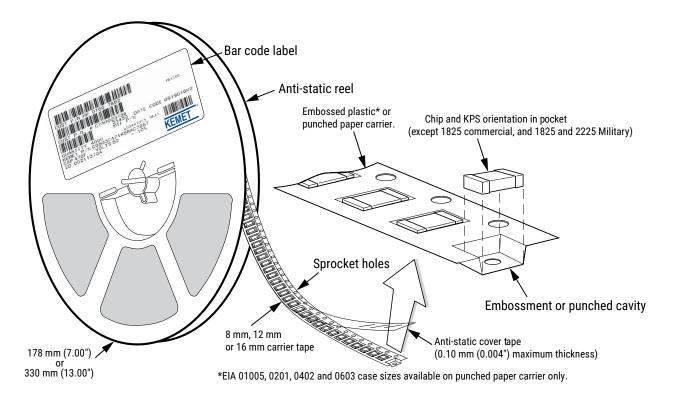
- COG, Ultra Stable X8R and Y5V dielectric devices
- · EIA 0402 case size devices
- EIA 0603 case size devices with Flexible Termination option.
- KPS Commercial and Automotive grade stacked devices.

These capacitors are supplied unmarked only.



#### **Tape & Reel Packaging Information**

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12 and 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.



### Table 5 – Carrier Tape Configuration, Embossed Plastic & Punched Paper (mm)

	Таре	<b>Embossed Plastic</b>		Punched Paper		
EIA Case Size	Size (W)*	7" Reel	13" Reel	7" Reel	13" Reel	
		Pitch (P <sub>1</sub> )*		Pitch (P <sub>1</sub> )*		
01005 - 0402	8			2	2	
0603	8			2/4	2/4	
0805	8	4	4	4	4	
1206 - 1210	8	4	4	4	4	
1805 - 1808	12	4	4			
≥ 1812	12	8	8			
KPS 1210	12	8	8			
KPS 1812 and 2220	16	12	12			
Array 0612	8	4	4			

\*Refer to Figures 1 and 2 for W and  $P_1$  carrier tape reference locations. \*Refer to Tables 6 and 7 for tolerance specifications.

#### New 2 mm Pitch Reel Options\*

Packaging Ordering Code (C-Spec)	Packaging Type/Options
C-3190	Automotive grade 7" reel unmarked
C-3191	Automotive grade 13" reel unmarked
C-7081	Commercial grade 7" reel unmarked
C-7082	Commercial grade 13" reel unmarked

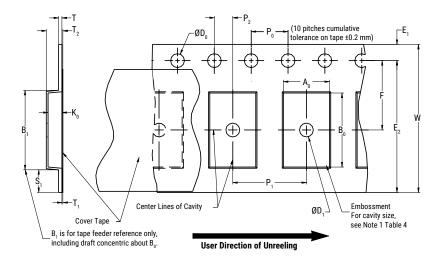
\* 2 mm pitch reel only available for 0603 EIA case size. 2 mm pitch reel for 0805 EIA case size under development.

#### Benefits of Changing from 4 mm to 2 mm Pitching Spacing

- Lower placement costs.
- Double the parts on each reel results in fewer reel changes and increased efficiency.
- Fewer reels result in lower packaging, shipping and storage costs, reducing waste.



# Figure 1 – Embossed (Plastic) Carrier Tape Dimensions



# Table 6 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm		1.0 (0.039)				25.0 (0.984)			
12 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.5	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm		(0.059)				(1.181)			
		,	Variable Dime	ensions — Mill	limeters (Inch	nes)			
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> ,B <sub>0</sub>	& K <sub>0</sub>
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)		
12 mm	Single (4 mm) and double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)	Not	te 5
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5 ±0.05 (0.138 ±0.002)	12.0 ±0.10 (0.157 ±0.004)	4.6 (0.181)	16.3 (0.642)		

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of the embossment location and the hole location shall be applied independently of each other.

2. The tape with or without components shall pass around R without damage (see Figure 6.)

3. If S<sub>1</sub> < 1.0 mm, there may not be enough area for a cover tape to be properly applied (see EIA Standard 481, paragraph 4.3, section b.)

4. B, dimension is a reference dimension for tape feeder clearance only.

5. The cavity defined by  $A_{\mu}$ ,  $B_{\mu}$  and  $K_{\mu}$  shall surround the component with sufficient clearance that:

(a) the component does not protrude above the top surface of the carrier tape.

(b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

(c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3.)

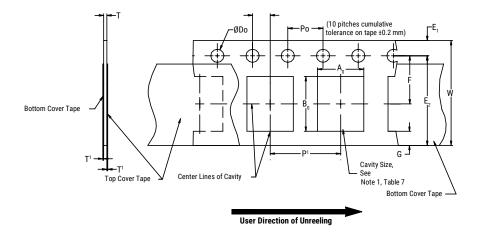
(d) lateral movement of the component is restricted to 0.5 mm maximum for 8 and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4.)

(e) for KPS product,  $A_{a}$  and  $B_{a}$  are measured on a plane 0.3 mm above the bottom of the pocket.

(f) see addendum in EIA Standard 481 for standards relating to more precise taping requirements.



### Figure 2 – Punched (Paper) Carrier Tape Dimensions



# Table 7 – Punched (Paper) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)								
Tape Size	D <sub>0</sub>	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	T <sub>1</sub> Maximum	G Minimum	R Reference Note 2	
8 mm	1.5 +0.10 -0.0 (0.059 +0.004 -0.0)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	0.10 (0.004) maximum	0.75 (0.030)	25 (0.984)	
	Variable Dimensions – Millimeters (Inches)							
Tape Size	Pitch	E2 Minimum	F	P <sub>1</sub>	T Maximum	W Maximum	$A_0 B_0$	
8 mm	Half (2 mm)	6.25	3.5 ±0.05 (0.138 ±0.002)	2.0 ±0.05 (0.079 ±0.002)	1.1 (0.098)	8.3 (0.327)	Note 1	
8 mm	Single (4 mm)	(0.246)		4.0 ±0.10 (0.157 ±0.004)		8.3 (0.327)	NOLE I	

1. The cavity defined by  $A_{\alpha}$ ,  $B_{\alpha}$  and T shall surround the component with sufficient clearance that:

a) the component does not protrude beyond either surface of the carrier tape.

b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

c) rotation of the component is limited to 20° maximum (see Figure 3.)

d) lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4.)

e) see addendum in EIA Standard 481 for standards relating to more precise taping requirements.

2. The tape with or without components shall pass around R without damage (see Figure 6.)



#### **Packaging Information Performance Notes**

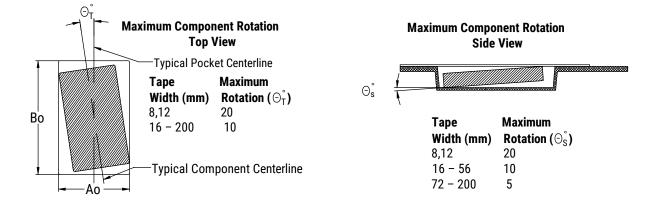
- 1. Cover Tape Break Force: 1.0 kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength		
8 mm	0.1 to 1.0 newton (10 to 100 gf)		
12 and 16 mm	0.1 to 1.3 newton (10 to 130 gf)		

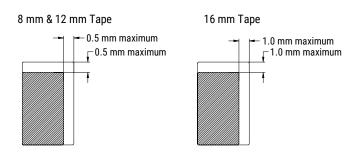
The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be  $165^{\circ}$  to  $180^{\circ}$  from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of  $300 \pm 10$  mm/minute.

**3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

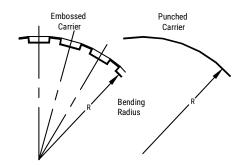
#### Figure 3 – Maximum Component Rotation



#### Figure 4 – Maximum Lateral Movement

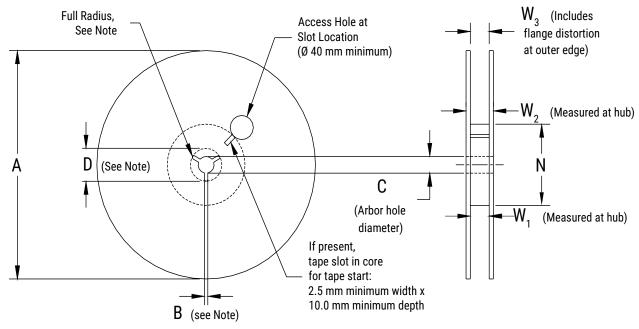


#### Figure 5 – Bending Radius





#### **Figure 6 – Reel Dimensions**



Note: Drive spokes optional; if used, dimensions B and D shall apply.

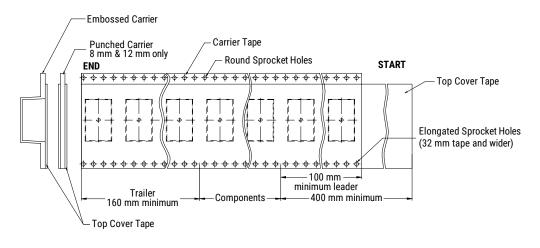
### Table 8 – Reel Dimensions

Metric will govern

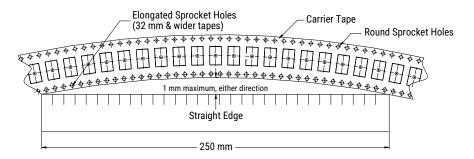
	Constant Dimensions — Millimeters (Inches)							
Tape Size	А	B Minimum	С	D Minimum				
8 mm	178 ±0.20		13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)				
12 mm	(7.008 ±0.008) or	1.5 (0.059)						
16 mm	330 ±0.20 (13.000 ±0.008)		()					
	Variable Dimensions – Millimeters (Inches)							
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>				
8 mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)					
12 mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference				
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)					



### Figure 7 – Tape Leader & Trailer Dimensions



# Figure 8 – Maximum Camber





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